

CLIPPEDIMAGE= JP02001110828A

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TITLE: MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE

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INVENTOR-INFORMATION:

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INT-CL (IPC): H01L021/56;H01L021/301 ;H01L023/12

ABSTRACT:

PROBLEM TO BE SOLVED: To improve the reliability of a chip size package.

SOLUTION: Metal posts 8 are formed to a wafer, and while a tape 21 for dicing is stuck to the back face of the wafer, the wafer is diced for each chip.

Then, the upper face of the wafer is resin-sealed, and a resin layer R is polished, and the head parts of the metal posts 8 are exposed. Then, solder balls are mounted on the metal posts 8, and the wafer is separated into each chip by a dicing process.

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PATENT ABSTRACTS OF JAPAN

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(71)Applicant : SONY CORP

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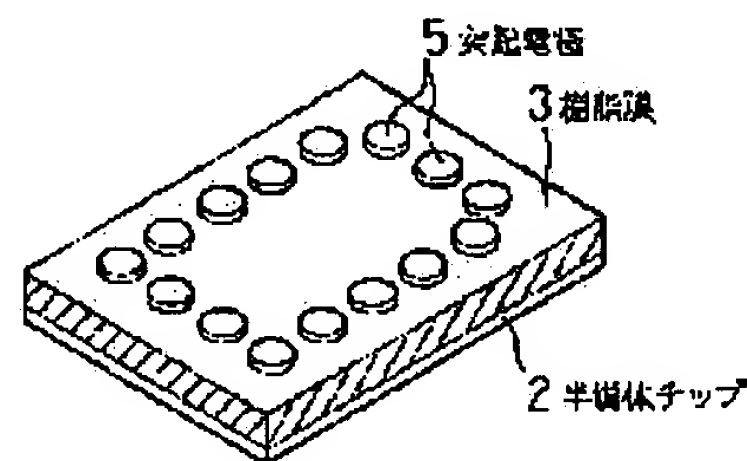
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(54) SEMICONDUCTOR DEVICE

(57)Abstract:

PURPOSE: To improve handling operability of a semiconductor chip in a manufacturing step while reducing in thickness of the chip itself irrespective of the size of a semiconductor wafer and to obtain a small-sized thin semiconductor device.

CONSTITUTION: A semiconductor wafer 1 is reduced in thickness while forming a resin film 3 in a protective reinforcing plate, protrusion electrodes 5 protrude from the film 3 on a semiconductor chip 2 as an external connection terminal, and the film 3 is so cut as to be the same in size as the chip 2. Thus, a semiconductor device having high reliability, easy handling, small size and thickness, is obtained.



LEGAL STATUS

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L Number	Hits	Search Text	DB	Time stamp
1	1252	(sog) and chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/24 14:26
2	1040	((sog) and chip) and (@ad<20000428)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/24 14:32
3	3477	glass near wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/24 14:31
4	0	glass near wafeL3 and chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/24 14:31
5	527	(glass near wafer) and chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/24 14:31
6	404	((glass near wafer) and chip) and (@ad<20000428)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/24 14:49
7	7894	wafer with (encapsulant or resin or protective)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/24 14:49
8	2170	(wafer with (encapsulant or resin or protective)) and chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/24 14:49
9	1750	((wafer with (encapsulant or resin or protective)) and chip) and (@ad<20000428)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/24 14:50
10	1023	((wafer with (encapsulant or resin or protective)) and chip) and (@ad<20000428)) and (chip with wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/07/24 15:02
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14	0	6407333.URPN.	USPAT	2002/07/24 15:00
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17	0	6291884.URPN.	USPAT	2002/07/24 15:05
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21	0	6344401.URPN.	USPAT	2002/07/24 15:18
22	1	("6291884").PN.	USPAT	2002/07/24 15:18
23	0	6162703.URPN.	USPAT	2002/07/24 15:22
24	0	6162703.URPN.	USPAT	2002/07/24 15:22

25	12	("3677875" "4722130" "4946716" "5071792" "5185292" "5223734" "5234535" "5476566" "5480842" "5494549" "5824595" "5888883").PN.	USPAT	2002/07/24 15:22
27	12	5989982.URPN.	USPAT	2002/07/24 15:29
28	0	2001308116.URPN.	USPAT	2002/07/24 16:34